



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2023-04-08
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32U545CET6Q	725B*455XXZ	A	998Z	2023-04-08
	Amount	UoM	Unit type	ST ECOPACK Grade
	179.60	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	7x7	48	L bend	
Comment	Package : 5B LQFP 48 7x7x1.4 1 0110596			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	725B*455XXXZ				6000000.0	1000000.3
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	10.137	mg	supplier	die	Silicon (Si)	7440-21-3		9.741	mg	960935	54238
				supplier	metallization	Aluminium (Al)	7429-90-5		0.044	mg	4341	245
				supplier	metallization	Copper (Cu)	7440-50-8		0.130	mg	12824	724
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	99	6
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.022	mg	2170	122
				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	592	33
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	99	6
				supplier	Passivation	Silicon Nitride	12033-89-5		0.031	mg	3058	173
				supplier	Passivation	Silicon Oxide	7631-86-9		0.161	mg	15882	896
Glue Epoxy (3230)	M-011 Other inorganic materials	1.379	mg	Supplier	Metals	Silver (Ag)	7440-22-4		1.124	mg	815000	6258
				Supplier	Plastics/polymers	2,2'-(Methylenebis(phenyleneoxymethylene))t	39817-09-9		0.041	mg	30000	230
				Supplier	Organic Compounds	Dihydro-3-(tetrapropenyl)furan-2,5-dione	26544-38-7		0.041	mg	30000	230
				Supplier	Organic Compounds	Epoxy resin	Proprietary		0.041	mg	30000	230
				Supplier	Organic Compounds	Dodecylloxirane	3234-28-4		0.041	mg	30000	230
				Supplier	Organic Compounds	Hexahydromethylphthalic anhydride	25550-51-0		0.041	mg	30000	230
				Supplier	Organic Compounds	Epoxy resin modifier	Proprietary		0.041	mg	30000	230
				Supplier	Metallic compounds	Copper oxide	1317-38-0		0.007	mg	5000	38
Mold Compound (EME-G631SHQ)	M-011 Other inorganic materials	115.204	mg	Supplier	Plastics/polymers	Epoxy Resin A	Trade Secret		2.419	mg	21000	13471
				Supplier	Plastics/polymers	Epoxy Resin B	Trade Secret		2.419	mg	21000	13471
				Supplier	Plastics/polymers	Phenol Resin	Trade Secret		6.451	mg	56000	35921
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		89.911	mg	780450	500623
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		13.285	mg	115320	73973
				Supplier	Non-metals	Carbon Black	1333-86-4		0.718	mg	6230	3996
Wire (Au)	Bonding Wire	0.802	mg	Supplier	Metals	Gold (Au)	7440-57-5		0.802	mg	1000000	4467
Plating anode (Pure Tin)	M-011 Other inorganic materials	1.078	mg	Supplier	Metals	Tin (Sn)	7440-31-5		1.078	mg	1000000	6004
Leadframe (C194+Ag)	Copper & its alloys	50.997	mg	Supplier	Metals	Copper (Cu)	7440-50-8		49.595	mg	972499	276144
				Supplier	Metals	Iron (Fe)	7439-89-6		1.153	mg	22601	6418
				Supplier	Metals	Zinc (Zn)	7440-66-6		0.077	mg	1500	426
				Supplier	Non-Metals	Phosphorus (P)	7723-14-0		0.015	mg	300	85
				Supplier	Metals	Silver (Ag)	7440-22-4		0.158	mg	3100	880